

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of Invention	METHOD AND STRUCTURE FOR HEAT SINK ATTACHMENT IN SEMICONDUCTOR DEVICE PACKAGING
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Application Number :

Confirmation Number:

First Named Applicant: Roger Lam

Attorney Docket Number: FIS920030398US1

Art Unit:

Examiner:

Search string: (5305185 or 5926371 or 6057597 or 6400565 or 20020070445).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5305185	1994-04-19	SAMAROV, ET AL.			
	2	5926371	1999-07-20	DOLBEAR			
	3	6057597	2000-05-02	FARNWORTH, ET AL.			
	4	6400565	2002-06-04	SHABBIR, ET AL.			

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020070445	2002-06-13	TARTER			

Signature

Examiner Name	Date